

Title (en)
Grinding or cleaning apparatus

Title (de)
Schleif-oder Putzeinrichtung

Title (fr)
Dispositif de meulage ou de polissage

Publication
EP 1092503 A3 20030917 (DE)

Application
EP 00810917 A 20001004

Priority
DE 19948996 A 19991011

Abstract (en)
[origin: EP1092503A2] Card wire is ground or cleaned by a grinding device incorporating an elastic layer (22), e.g. expanded foam, with a grinding medium (23), e.g. corundum particles, embedded throughout the material. The wire penetrates partly into the material. The device can be a complete or sectionalized roller and suction is provided to remove abraded material.

IPC 1-7
B24B 19/18; **B24D 13/12**

IPC 8 full level
B24B 19/18 (2006.01); **B24D 13/02** (2006.01); **D01G 15/38** (2006.01)

CPC (source: EP US)
B24B 19/18 (2013.01 - EP US); **B24D 13/02** (2013.01 - EP US); **D01G 15/38** (2013.01 - EP US)

Citation (search report)
• [DXY] DE 19739187 A1 19990311 - TRUETZSCHLER GMBH & CO KG [DE]
• [YA] WO 9916579 A1 19990408 - RIETER AG MASCHF [CH], et al
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• [X] US 4504283 A 19850312 - CHARVAT VERNON K [US]
• [X] DE 4026336 A1 19920227 - JASON INC [US]
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Designated contracting state (EPC)
AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE

DOCDB simple family (publication)
DE 19948996 A1 20010412; EP 1092503 A2 20010418; EP 1092503 A3 20030917; US 6508698 B1 20030121

DOCDB simple family (application)
DE 19948996 A 19991011; EP 00810917 A 20001004; US 66480300 A 20000919